5-147727-8 - ACTIVE

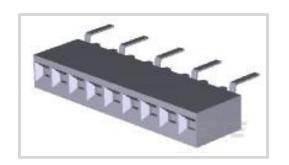
AMPMODU | Modu Connector System

TE Internal #: 5-147727-8 PCB Mount Receptacle, Vertical, Board-to-Board, 9 Position, .1 in [2.54 mm] Centerline, Tin, Through Hole - Solder, Signal, Modu Connector System

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **9**

Number of Rows: 1

Features

Product Type Features

Applied Pressure

PCB Connector Assembly Type

Connector System

Standard

PCB Mount Receptacle

Board-to-Board

Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	9
Number of Rows	1
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	750 Vrms
Operating Voltage	333 VAC
Body Features	
Connector Profile	Low
Primary Product Color	Black

PCB Mount Receptacle, Vertical, Board-to-Board, 9 Position, .1 in [2.54 mm] Centerline, Tin, Through Hole - Solder, Signal, Modu Connector System



Contact Features

Contact Layout	Inline
Contact Protection Type	Closed Entry Housing
Mating Square Post Dimension	.64 mm[.025 in]
	150 – 300 µin
Contact Shape & Form	Short Point
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Tin
Contact Mating Area Plating Material Thickness	3.81 – 7.62 μm[150 – 300 μin]
Contact Type	Socket
Contact Current Rating (Max)	2 A
Termination Features	
Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Rectangular Termination Post & Tail Width	.69 mm[.027 in]
Termination Post & Tail Length	3.18 mm[.125 in]
Termination Method to Printed Circuit Board	Through Hole - Solder

Mechanical Attachment

Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Mating Entry Location	Bottom & Top
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Polyester - GF
Dimensions	
Connector Height	6.73 mm[.265 in]
Stack Height	9.02 mm[.355 in]
PCB Thickness (Recommended)	1.4 – 2.4 mm[.055 – .094 in]
Usage Conditions	
Housing Temperature Rating	Standard

PCB Mount Receptacle, Vertical, Board-to-Board, 9 Position, .1 in [2.54 mm] Centerline, Tin, Through Hole - Solder, Signal, Modu Connector System



Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Approved Standards	CSA LE7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	25
Packaging Type	Box, Tube
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224)

Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed

Not Low Halogen - contains Br or Cl > 900 ppm.

Solder Process Capability

Halogen Content

Wave solder capable to 265°C

Product Compliance Disclaimer

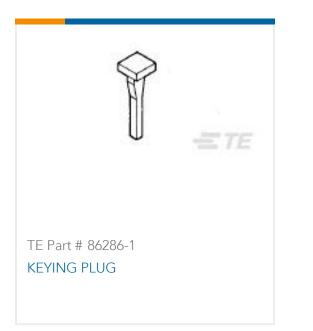
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

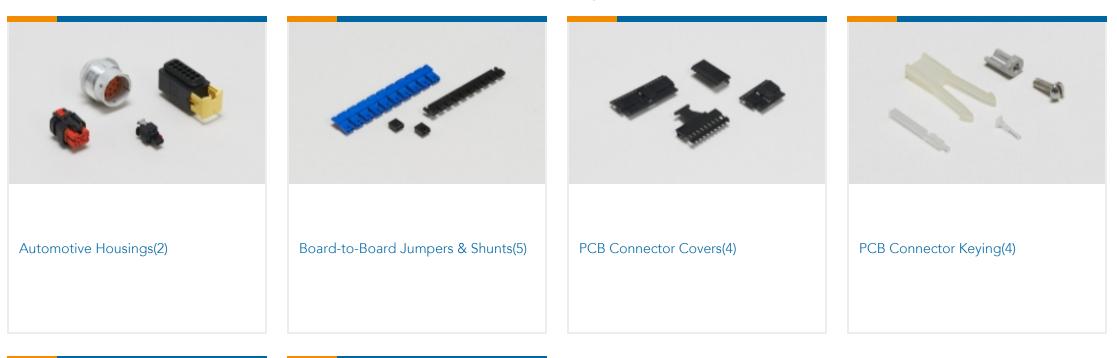
& For support call+1 800 522 6752

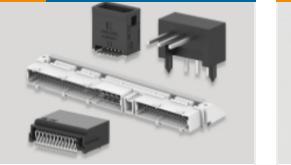
PCB Mount Receptacle, Vertical, Board-to-Board, 9 Position, .1 in [2.54 mm] Centerline, Tin, Through Hole - Solder, Signal, Modu Connector System





Also in the Series | Modu Connector System









Customers Also Bought





PCB Mount Receptacle, Vertical, Board-to-Board, 9 Position, .1 in [2.54 mm] Centerline, Tin, Through Hole - Solder, Signal, Modu Connector System



Documents

CAD Files Customer View Model ENG_CVM_CVM_5-147727-8_M.2d_dxf.zip English 3D PDF 3D Customer View Model ENG_CVM_CVM_5-147727-8_M.3d_igs.zip English Customer View Model

ENG_CVM_CVM_5-147727-8_M.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION5_CONT

English

Product Environmental Compliance TE Material Declaration

English